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Cited Documents: DE4037876; US5355008; US3667008; EP0624909

## Abstract

To reduce the distributed resistance in an integrated circuit die, a relatively thick metal strap layer is deposited on a bus or other conductive path in the top metal layer. The metal strap layer is formed by etching a longitudinal channel in the passivation layer over the bus and plating a thick metal layer, preferably nickel, in the channel. The metal strap layer dramatically reduces the resistance of the bus.

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Foil Resistors | Measurements Group | Roederstein | Sensortronics | Sfernice | Siliconix | Sprague | Spectrol  
Tansitor | Techno | Telefunken | Thin Film | Ultronic | Vitramon

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